



3.3V, 1-port, SATA Gen 3i ReDriver™ with Adjustable Equalization/Pre-Emphasis

Features

- → Supports SATA Gen 3i.
- → Two 6Gbps differential signal pairs
- → 100Ω Differential CML I/O's
- → Input signal level detect and squelch for each channel
- → OOB Support
- → Automatic HDD Rate detection for output swing/emphasis setting
- → Termination detect indication
 - Power saving mode control to Host or HDD
- → Adjustable Receiver Equalization
- → Selectable Output Pre-emphasis and Swing Control
- → High impedance I/O termination in standby mode
- → ESD +/-8kV
- → Low Power Operation: 254mW typical
- → Auto-Slumber Mode: 36mW typical
- → HDD unplugged: 3.6mW
- → Power down Stand-by Mode: 0.7mW max
- → Supply Voltage: 3.3V ±10%
- → Industrial Temperature Range: -40°C to 85°C
- → Packaging: 20-TQFN (4x4mm)

Description

The PI3EQX6741ST is a low power, signal SATA Gen 3i 6Gbps ReDriver. The device provides programmable equalization and output emphasis, to optimize performance over a variety of physical mediums by reducing Inter-Symbol Interference. PI3EQX6741ST supports two 100Ω Differential CML data I/O's between the Protocol ASIC to a switch fabric, across a backplane, or to extend the signals across other distant data pathways on the user's platform.

The integrated equalization circuitry provides flexibility with signal integrity of the signal before the ReDriver.

A low-level input signal detection and output squelch function is provided for each channel. Each channel operates fully independently. When the channels are enabled (EN=1) and operating, that channels input signal level (on xI+/-) determines whether the output is active. If the input signal level of the channel falls below the active threshold level (Vth-) then the outputs are driven to the common mode voltage.

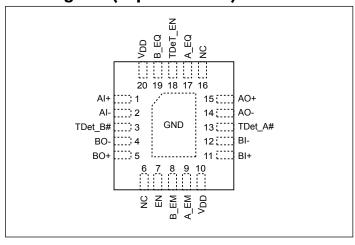
Termination Detect indication (TDet_A# or TDET_B#) provides indication when the load is connected ie HDD or Host. This can be used as control to go into power saving mode by either the host or HDD.

In addition to signal conditioning, when EN = 0, the device enters a low power standby mode.

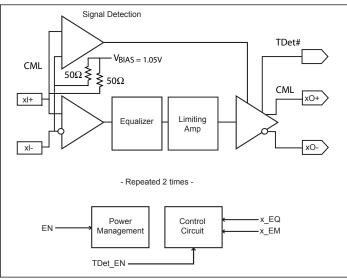
Applications

→ Notebook, desktop, docking station, Set Top Box, Server Workstation, Data Storage

Pin Diagram (Top Side View)



Block Diagram







Pin Description

Standard Mode Pin #	Pin	True	Description
Mode Pin #	Name	Type	Description
9	A_EM	Input	Output emphasis adjustment for channel A. (See Configuration Table) Digital control with $200 \mathrm{K}\Omega$ pull-up resistor.
17	A_EQ	Input	Channel A Equalization adjustment is active. (See Configuration Table) Tri-level input pin with $100K\Omega$ pull-up and $100K\Omega$ pull-down resistors.
1 2	AI+ AI-	Input	CML input forward channel A with internal 50 Ω pull-up resistors connected to VBIAS (100 Ω differential).
15 14	AO+ AO-	Output	CML output channel A with internal 50 Ω pull-up resistors connected to VBIAS (100 Ω differential).
8	B_EM	Input	Output emphasis adjustment for channel B. (See Configuration Table) Digital control with $200 \mathrm{K}\Omega$ pull-up resistor.
19	B_EQ	Input	Tri-level input pin with $100 \mathrm{K}\Omega$ pull-up and $100 \mathrm{K}\Omega$ pull-down resistors. (See Configuration Table)
11 12	BI+ BI-	Input	CML input return channel B with internal 50K Ω pull-up, resistor connected to VBIAS (100 Ω differential).
5 4	BO+ BO-	Output	Positive CML output channel B with internal 50Ω pull-up resistor connected to VBIAS (100Ω differential).
7	EN	Input	Chip Enable "High" provides normal operation. "Low" for power down mode. With internal $200 \mathrm{K}\Omega$ pull-up resistor.
Center Pad	GND	GND	Supply ground.
10, 20	V _{DD}	Power	3.3V supply voltage ± 10%
3	TDet_B#	Output	Termination detect output for channel B-Active Low, open drain. Low: HDD Termination present. High: HDD Termination NOT present.
13	TDet_A#	Output	Termination detect output for channel A-Active Low, open drain. Low: HDD Termination present. High: HDD Termination NOT present.
			Termination Detect Enable (200K Ω internal pull-up resistor)
18	TDet_EN	Input	High: Enable Termination Detect for eSATA application or hot plug Device application
			Low: Disable Termination Detect for internal SATA application.
6, 16	NC		No Connection internally.





Configuration Table - Output Pre-emphasis/Swing Setting

A_EM/B_EM	3 Gb/s	6 Gb/s		
0	550mV pp	650mV pp		
1	550mV pp + 3dB Pre-emphasis	650mV pp + 1.5dB Pre-emphasis		

Configuration Table - Input Equalizer

A_EQ/B_EQ	1.5 Gb/s	3 Gb/s	6Gb/s
0	1 dB	2.5 dB	3 dB
floating	2.5 dB	5 dB	6 dB
1	4 dB	7.5 dB	9 dB

Termination Detect Feature:

Termination Detect is a power saving feature. The user can enable TDet_EN (set to High) for eSATA application as it would save more power when there is no external HDD connection. But for internal SATA application, TDet_EN should be set to LOW because internal HDD is always on and termination is always there.

When Redriver doesn't detect Host or HDD termination, there will be about 12us detect pulse width with 50us detect period at the output of ReDriver. Once the termination is detected, the detect period will change to about 40ms. Anyway when the signal is detected at the input of redriver, there will not be any detect pulse at both the output side of redriver.

01/04/17





Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

Storage Temperature65°C to +150°C
Supply Voltage to Ground Potential0.5V to +4.6V
DC SIG Voltage0.5V to V_{DD} +0.5V
Output Current25mA to +25mA
Power Dissipation Continuous
Operating Temperature40°C to +85°C
ESD, Human Body Model8kV to 8kV

Note:

Stresses greater than those listed under MAXIMUM RAT-INGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

AC/DC Electrical Characteristics

Symbol	Parameter	Conditions	Min.	Typ. (1)	Max.	Units	
VDD	Power Supply Voltage		3.0		3.6	V	
PSTANDBY	Supply Power, Standby	EN = 0		0.07	0.7		
PUNPLUG	Supply Power, HDD unplugged	No HDD attached, TDet_EN = High		3.6	11		
PSLUMBER	Supply Power, Slumber	TDet_EN = Low		36	50	mW	
PACTIVE	Supply Power, Active	$EN = 1$ A/B_EM=0 DIFFP-P \geq VTH-SD		254	317		
IDD-STANDBY	Supply Current Standby	EN = 0		0.02	0.2		
IDD-UNPLUG	Supply Current, HDD unplugged	No HDD attached, TDet_EN = High		1	3		
IDD-SLUMBER	Supply Current Slumber	TDet_EN = Low		11	14	mA	
T	Supply Current Active	EN = 1, input = 600mVppd,		77	88		
I _{DD-ACTIVE}		A/B_EM=0					
tPD	Latency	From input to output		0.7		ns	
CML Receiver	Input						
Z _R X-DC	DC Input Impedance		40	50	60		
Z _R X-DIFF-DC	DC Differential Input Impedance		80	100	120	Ohm	
VRX-DIFFp-p	Differential Input Peak-to-peak Voltage		0.2		1.2	V	
VRX-CM-ACP	AC Peak Common Mode Input Voltage				150	mV	
V _{TH-SD}	Signal detect Threshold	EN = 1	50		200 ⁽²⁾	mVppd	

Note:

- 1. Typical values are at VDD = 3.3V, TA = 25°C ambient and maximum loading.
- 2. Using Compliance test at 1.5Gbps, 3Gbps and 6Gbps. Also using OOB (OOB is formed by ALIGNp primitive or D24.3) test patterns at 1.5Gbps. The ALIGN primitive (K28.5+D10.2+D27.3=0011111010+0101010101+0010011100). The D24.3 = 00110011001100110011.





AC/DC Electrical Characteristics (CML Receiver Input continued)

Symbol	Parameter	Conditions		Min.	Typ. ⁽¹⁾	Max.	Units	
		75MHz-300MHz		18				
	RX differential mode return loss	300MHz-600MH	z	14				
DI 1111 DV		600MHz-1.2GHz		10			dB	
RL _{dd11_RX}	KA differential filode return loss	1.2GHz-2.4GHz		8			ив	
		2.4GHz-3.0GHz		3				
		3.0 GHz-5.0GHz		1				
		150MHz - 300M		3				
		300MHZ - 600M		5				
RL _{cc11_RX}	RX common mode return loss	600MHz - 1.2GH		2			dB	
_		1.2GHz - 2.4GHz 2.4GHz - 3.0GHz		2				
		3.0GHz - 5.0GHz		1				
		150MHz - 300M 300MHz - 600M		30 30				
		600MHz - 1.2GH		20				
RL _{dc11_RX}	RX impedance balance	1.2GHz - 2.4GHz		10			dB	
		2.4GHz - 3.0GHz		4				
		3.0GHz - 5.0GHz	Z	4				
CML Transmitt Z _{TX-DIFF-DC}	ter Output (100Ω differential) ⁽³⁾ DC Differential TX Impedance			80	100	120	Ohm	
21X-DIFF-DC	1		SATA2	450	100	700		
V _{TX-DIFFp-p}	Differential Peak-to-peak Output Voltage	$V_{TX-DIFFp-p} = 2$ $* V_{TX-D}$	SATA3	550		750	mV	
V _{TX-C}	Common-Mode Voltage	$ V_{TX-D} + V_{TX-I}$		0.5		1.2	V	
t _F , t _R	Transition Time	20% to 80% ⁽³⁾ 0d	•	40		150	ps	
V _{amp_bal}	TX amplitude imbalance	3G only; HFTP, N		10		10	%	
T _{skew}	TX differential skew	1.5G and 3G; HF				20	ps	
V _{cm_ac}	TX AC common mode voltage	3G only; MFTP				50	mVpp	
		·			3			
V _{TX-Pre-Ratio-max}	Max TX Pre-emphasis Level				1.5		dB	
RL _{dd11_TX}	TX differential mode return loss	150MHz - 300M	Hz	14				
		300MHz - 600M		8			dB	
		600MHz - 1.2GH		6				
		1.2GHz - 2.4GHz		6				
		2.4GHz - 3.0GHz		3				
<u> </u>	AC Counting Counciton	3.0 GHz - 5.0GH	Z	1	4.7	12	Г	
C_{TX}	AC Coupling Capacitor		10"	2	4.7	12	nF	
T_{J}	Total Jitter	FR4 Input Trace	18"			0.16	UI	
,	,	•	36"			0.24		
D_{J}	Deterministic Jitter	FR4 Input Trace	18"			0.11	UI	
D _J		1 K4 Input ITace	36"			0.19		

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Note:

3. Recommended output coupling capacitor is 4.7nF to 12nF (on each output)





AC/DC Electrical Characteristics

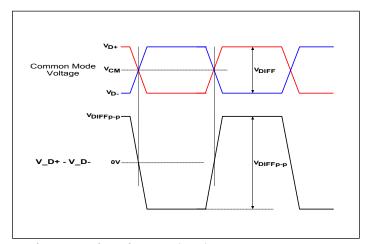
Symbol	Parameter	Conditions	Min.	Typ. (1)	Max.	Units
		150MHz - 300MHz	5			
		300MHz - 600MHz	5			dB
RL _{cc11_TX}	TX common mode return loss	600MHz – 1.2GHz	2			
RECCII_IX	172 common mode return 1035	1.2GHz – 2.4GHz	2			
		2.4GHz – 3.0GHz	1			
		3.0 GHz – 5.0GHz	1			
		150MHz – 300MHz	30			
		300MHz - 600MHz	20			
RL _{dc11_TX}	TX impedance balance	600MHz – 1.2GHz	10			dB
KLacII_IX	1 X Impedance balance	1.2GHz – 2.4GHz	10			ав
		2.4GHz – 3.0GHz	4			
		3.0 GHz – 5.0GHz	4			
LVCMOS Cor	Input High Voltage (Bi-Level)		0.65 ×			
' In	imput fright voltage (bi Level)		V_{DD}			V
$V_{\rm IL}$	Input Low Voltage (Bi-Level)				$0.35 \times V_{DD}$	V
I_{IH}	Input High Current				100	4
I_{IL}	Input Low Current		-100			μΑ
V _{OL}	DC Output Logic Low	$I_{OL} = 4 \text{ mA}$			0.4	V
V _{IH}	Input High Voltage (Tri-Level)		0.8 ×V _{DD}			V
V_{IL}	Input Low Voltage (Tri-Level)				$0.2 \times V_{\mathrm{DD}}$	V

Auto Slumber Mode Entry/Exit Time

Symbol	Parameter	Conditions	Min.	Typ. ⁽¹⁾	Max.	Units
T _{SlumberON}	Entry time to Slumber Mode	Electrical Idle at Input (See Figure)		10	20	μS
T _{SlumberOFF}	Exit time from Slumber Mode	After first signal activity (See Figure)		6	20	ns







Pre-emphasis = 20·Log(V_{DIFF-PRE}/V_{DIFF})

V_{D+}

V_D

V_D

V_D

V_D

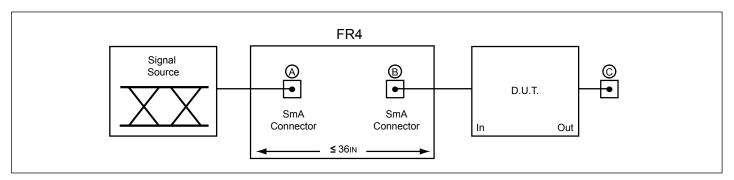
V_D

1stT_{BIT}

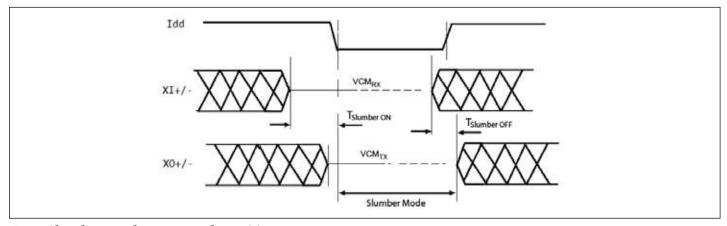
2nd +T_{BIT}(s)

Definition of Differential Voltage and Differential Voltage Peak-to-Peak

Definition of Pre-emphasis



Test Condition Referenced in the Electrical Characteristic Table

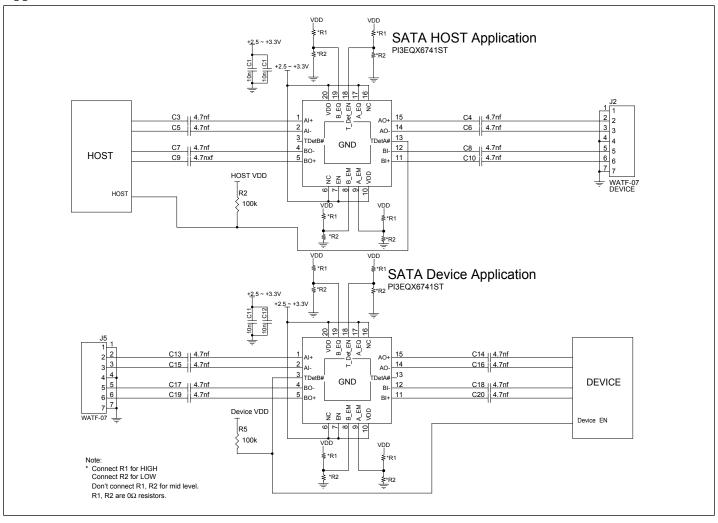


Auto Slumber Mode Entry and Exit Timing





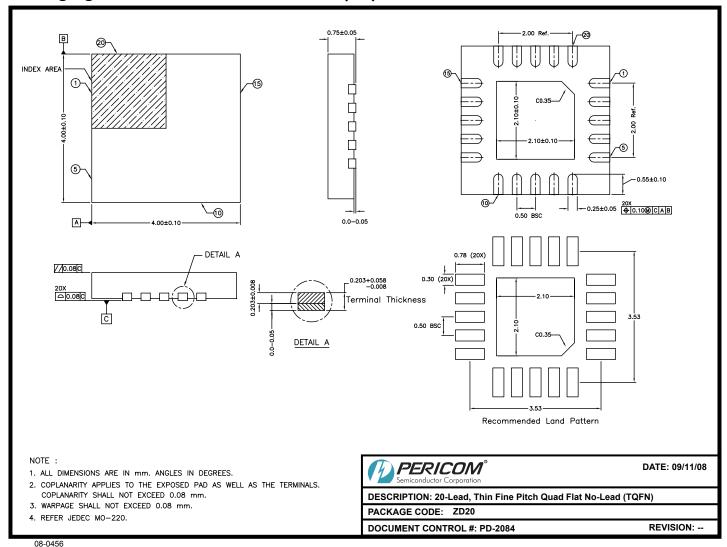
Application Schematic







Packaging Mechanical: 20-contact TQFN (ZD)



Note: For latest package info, please check: http://www.pericom.com/support/packaging/packaging-mechanicals-and-thermal-characteristics/

Ordering Information

Ordering Number	Package Code	Package Description
PI3EQX6741STZDE ZD .		20-Lead, Thin Fine Pitch Quad Flat No-Lead (TQFN)
PI3EQX6741STZDEX ZD		20-Lead, Thin Fine Pitch Quad Flat No-Lead (TQFN), Tape & Reel

Notes:

- Thermal characteristics can be found on the company web site at www.pericom.com/packaging/
- E = Pb-free and Green
- X suffix = Tape/Reel





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